MA3S781D (MA781WA), MA3S781E (MA781WK)

Silicon epitaxial planar type

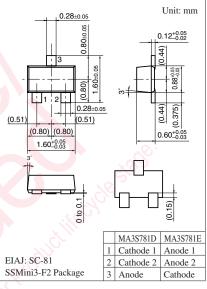
For high speed switching

Features

- Two MA3S781 (MA781) is contained in one package
- High-density mounting is possible
- \bullet Low forward voltage $V_{\rm F}$

Parameter		Symbol	Rating	Unit	
Reverse voltage		VR	30	v	
Maximum peak reverse voltage		V _{RM}	30	V	
Forward current	Single	I _F	30	mA	
	Double		20		
Peak forward current	Single	I _{FM}	150	mA	
	Double		110		
Junction temperature		Tj	125	°C	
Storage temperature		T _{stg}	-55 to +125	°C	

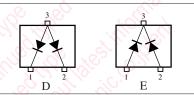
Absolute Maximum Ratings $T_a = 25^{\circ}C$



Marking Symbol

• MA3S781D: M2P • MA3S781E: M2R

Internal Connection



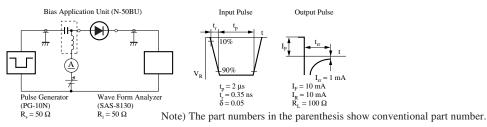
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _{F1}	$I_F = 1 \text{ mA}$	SI.		0.4	V
	V _{F2}	$I_F = 30 \text{ mA}$	<u>0.</u> X		1.0	
Reverse current	I _R	$V_R = 30 V$			1	μΑ
Terminal capacitance	Ct	$V_R = 1 V, f = 1 MHz$		1.5		pF
Reverse recovery time	t _{rr}	$I_F = I_R = 10 \text{ mA}$		1.0		ns
		$I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$				
Detection efficiency	η	$V_{IN} = 3 V_{(peak)}$, f = 30 MHz		65		%
		$R_{L} = 3.9 \text{ k}\Omega, C_{L} = 10 \text{ pF}$				

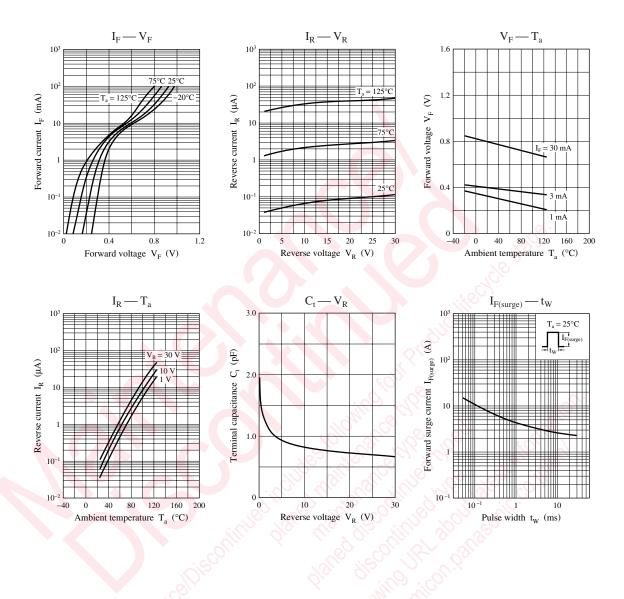
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

 This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 2 GHz. 4. *: trr measurement circuit



Panasonic



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